

Title (en)

METHOD FOR MAKING AN EMISSIVE CATHODE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER EMISSIONSKATHODE

Title (fr)

PROCEDE DE FABRICATION D'UNE CATHODE EMISSIVE

Publication

**EP 1885649 A2 20080213 (FR)**

Application

**EP 06820247 A 20060529**

Priority

- FR 2006050490 W 20060529
- FR 0551412 A 20050530

Abstract (en)

[origin: FR2886284A1] The method involves providing a substrate (100) comprising a surface layer (101) on one of its sides, and covering the surface layer by a catalyst layer (102) structured according to a pattern appearing on areas of the surface layer covered and not covered by the catalyst layer. The surface layer is etched in the non-covered areas. Nanostructures are selectively grown on the zones covered by the catalyst layer. Independent claims are also included for the following: (1) a device including an anode and a cathode comprising electrical independent nanostructures (2) a flat-panel field emission display comprising a cathode structure.

IPC 8 full level

**B82B 3/00** (2006.01); **B82B 1/00** (2006.01); **H01J 1/304** (2006.01); **H01J 9/02** (2006.01)

CPC (source: EP US)

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Citation (search report)

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